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(12) United States Design Patent

Lin et al.

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(54) **LIQUID-COOLING HEAT DISSIPATION MODULE**

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(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179, 182.184; D23/231; D14/230
CPC . H01Q 1/428; H01Q 1/02; H01Q 1/38; H01L 23/367; H01L 23/3672; H05K 7/20254; H05K 7/20263; H05K 7/20409; F28F 3/022; F28F 3/04; F28F 21/065; G02B 1/111; F28D 15/0275
See application file for complete search history.

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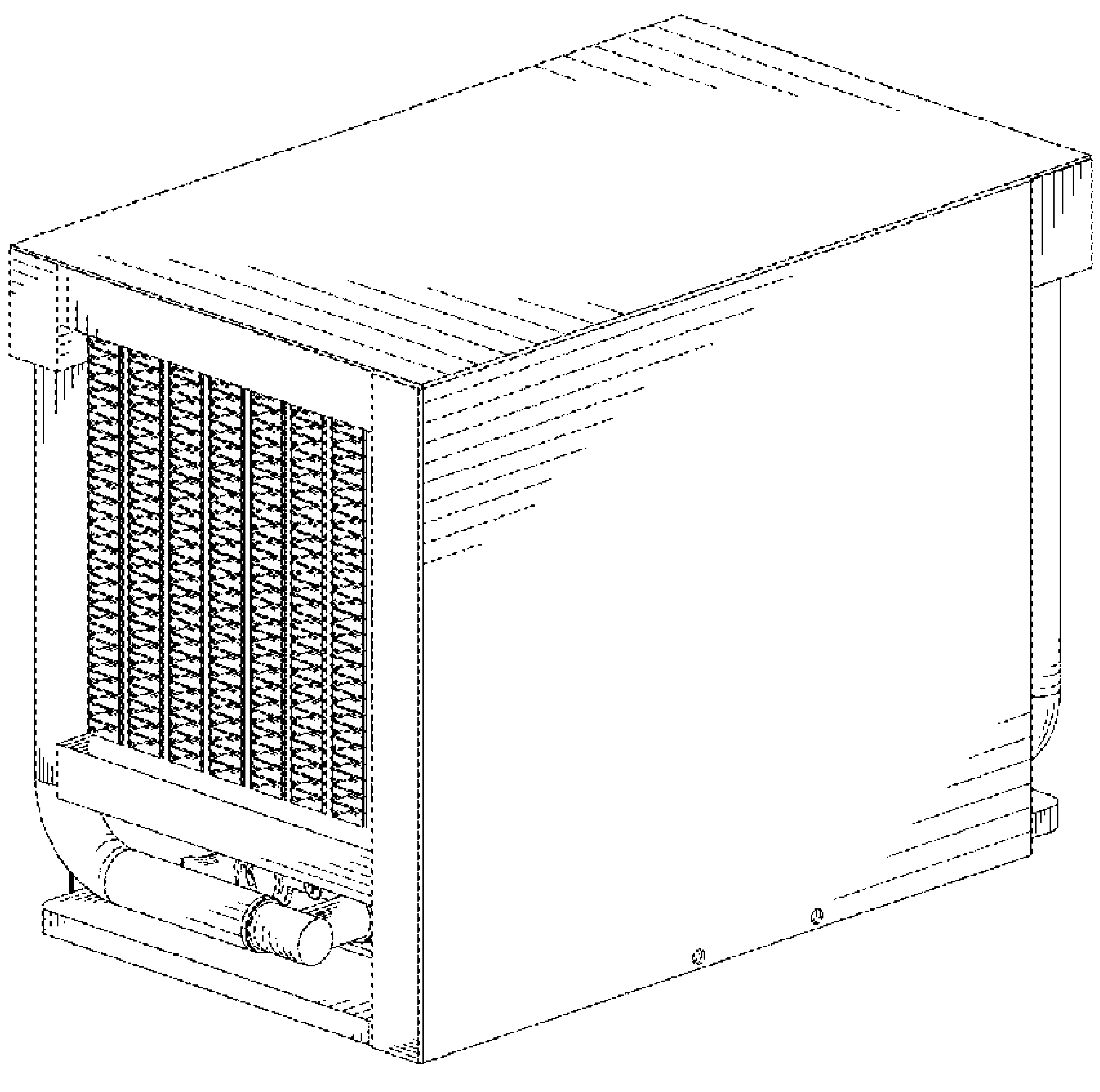
(57) **CLAIM**

The ornamental design for a liquid-cooling heat dissipation module, as shown and described.

DESCRIPTION

FIG. **1** is a front, top, right perspective view of a liquid-cooling heat dissipation module showing our new design;
FIG. **2** is a back, top, left perspective view thereof;
FIG. **3** is a front, bottom, right perspective view thereof;
FIG. **4** is a front elevational view thereof;
FIG. **5** is a rear elevational view thereof;
FIG. **6** is a left side elevational view thereof;
FIG. **7** is a right side elevational view thereof;
FIG. **8** is a top plan view thereof; and,
FIG. **9** is a bottom plan view thereof.
The broken lines in the drawings illustrate portions of the liquid-cooling heat dissipation module which form no part of the claimed design.

1 Claim, 9 Drawing Sheets



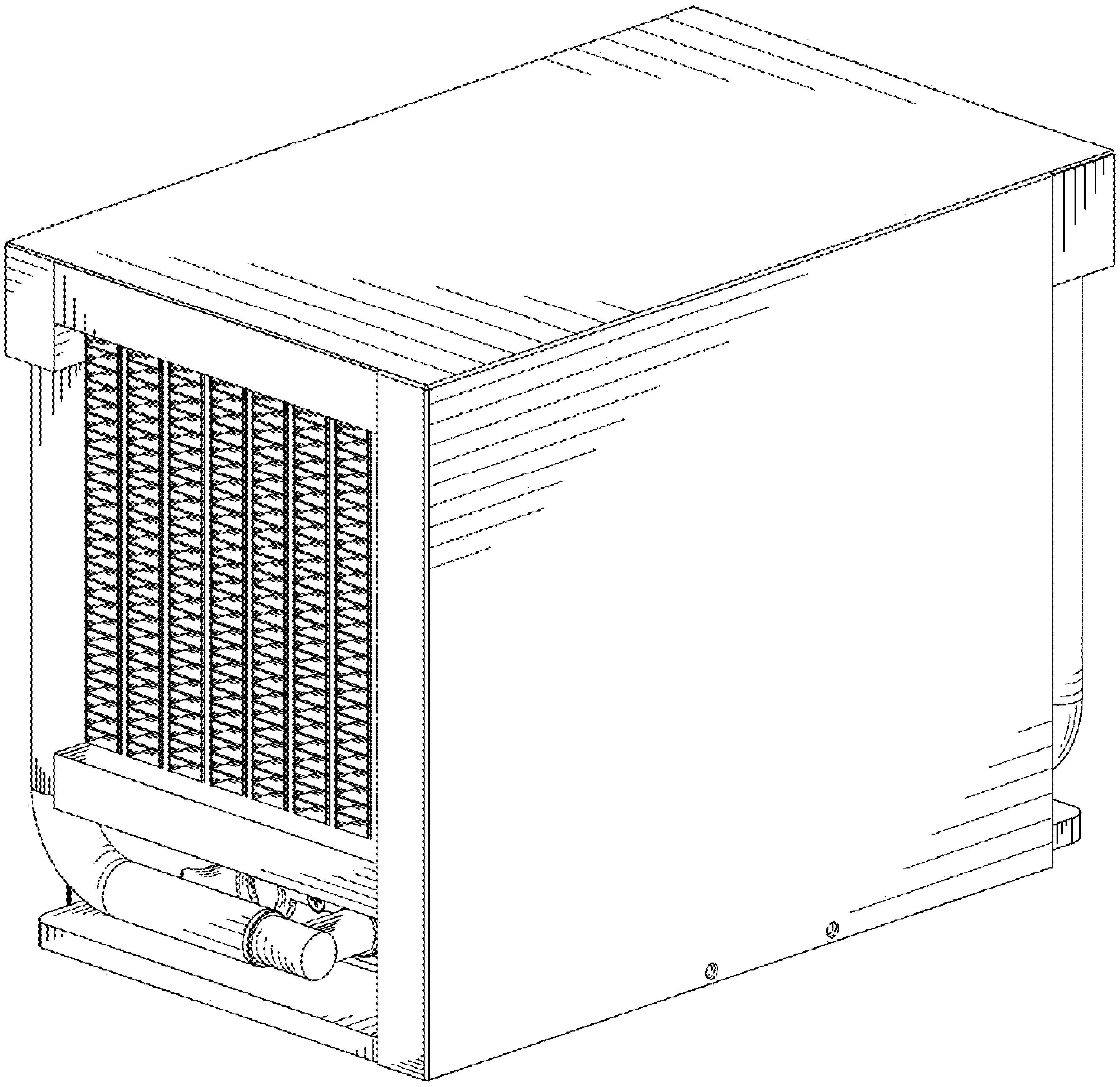


Fig. 1

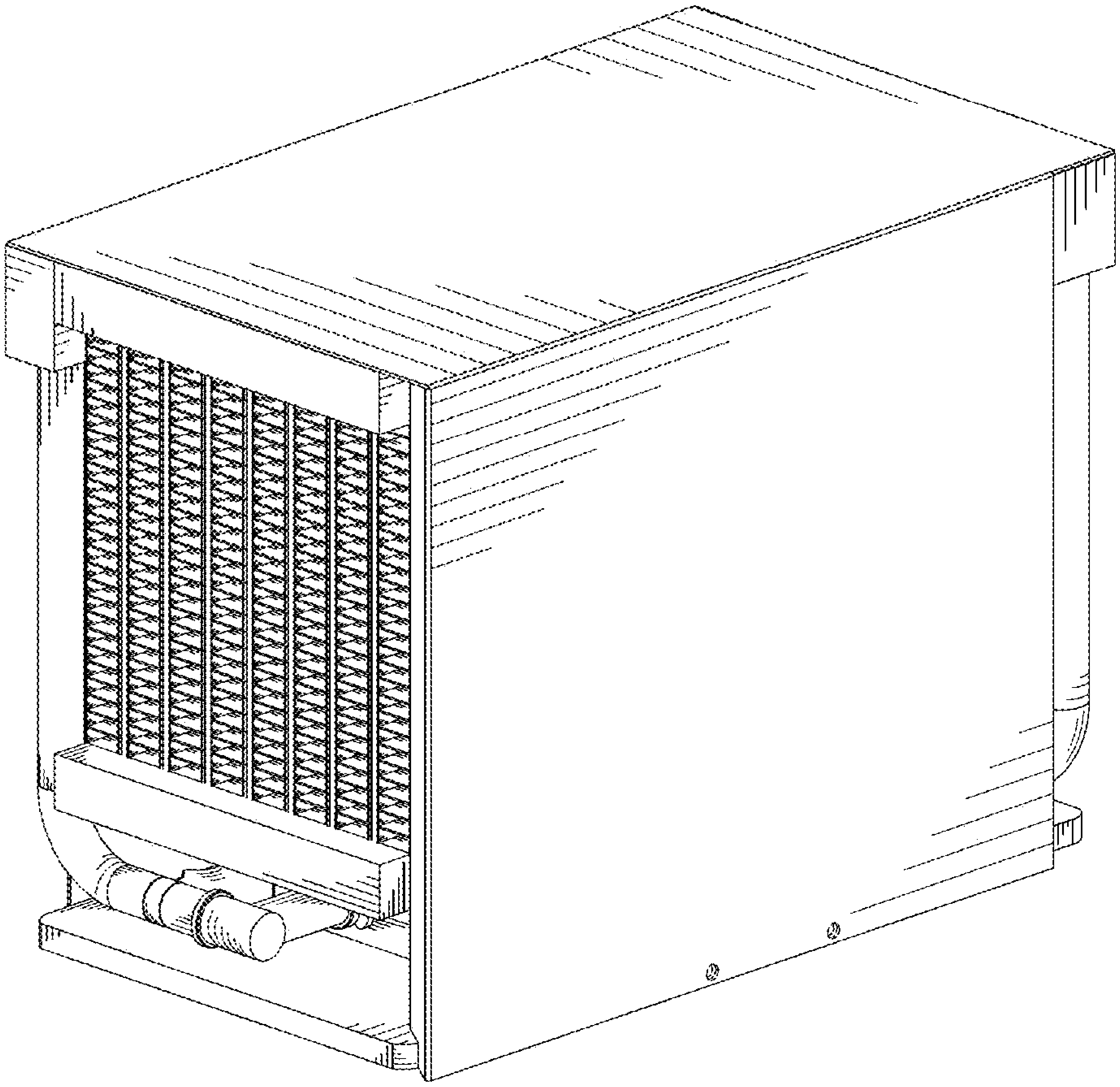


Fig. 2

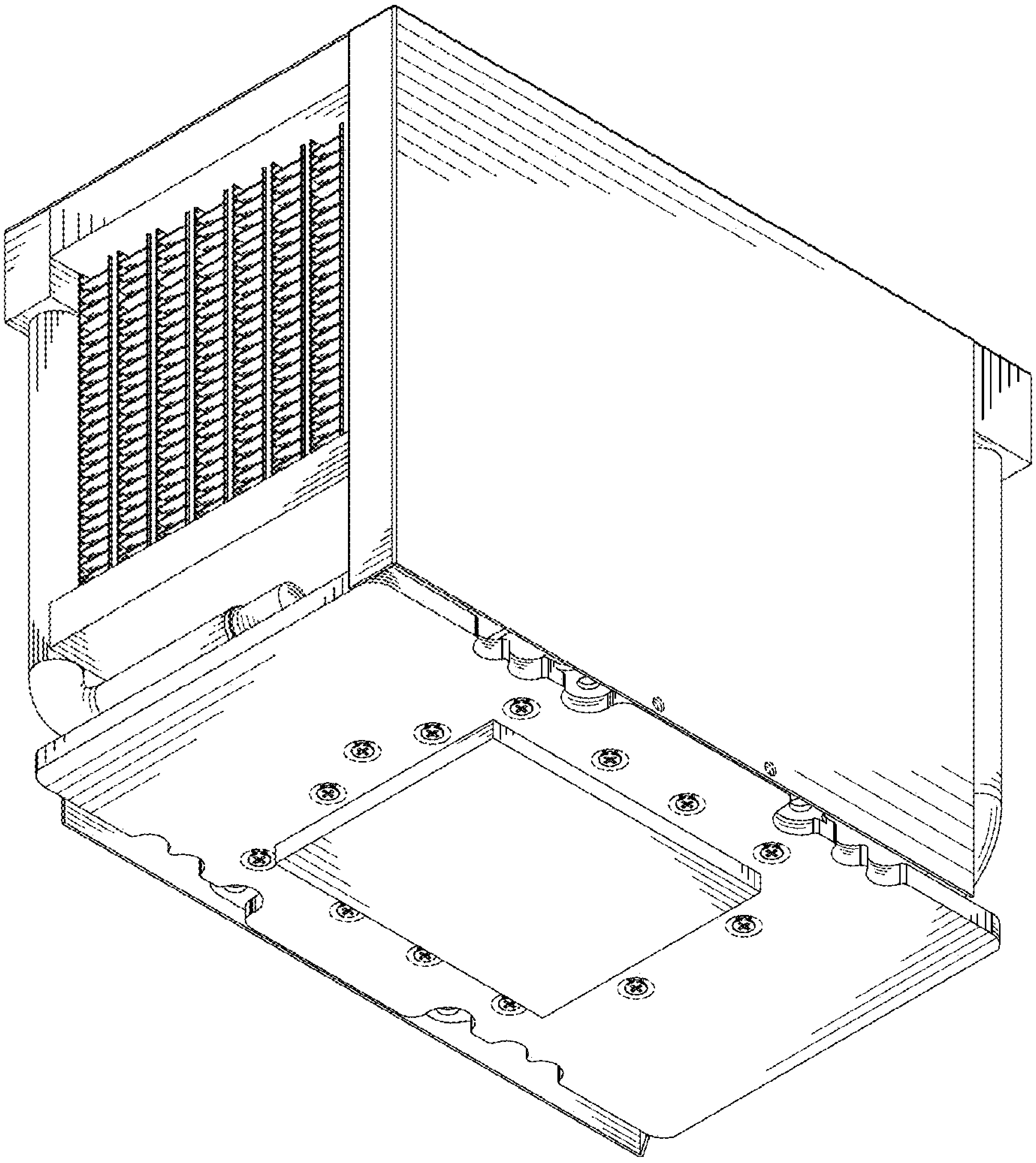


Fig. 3

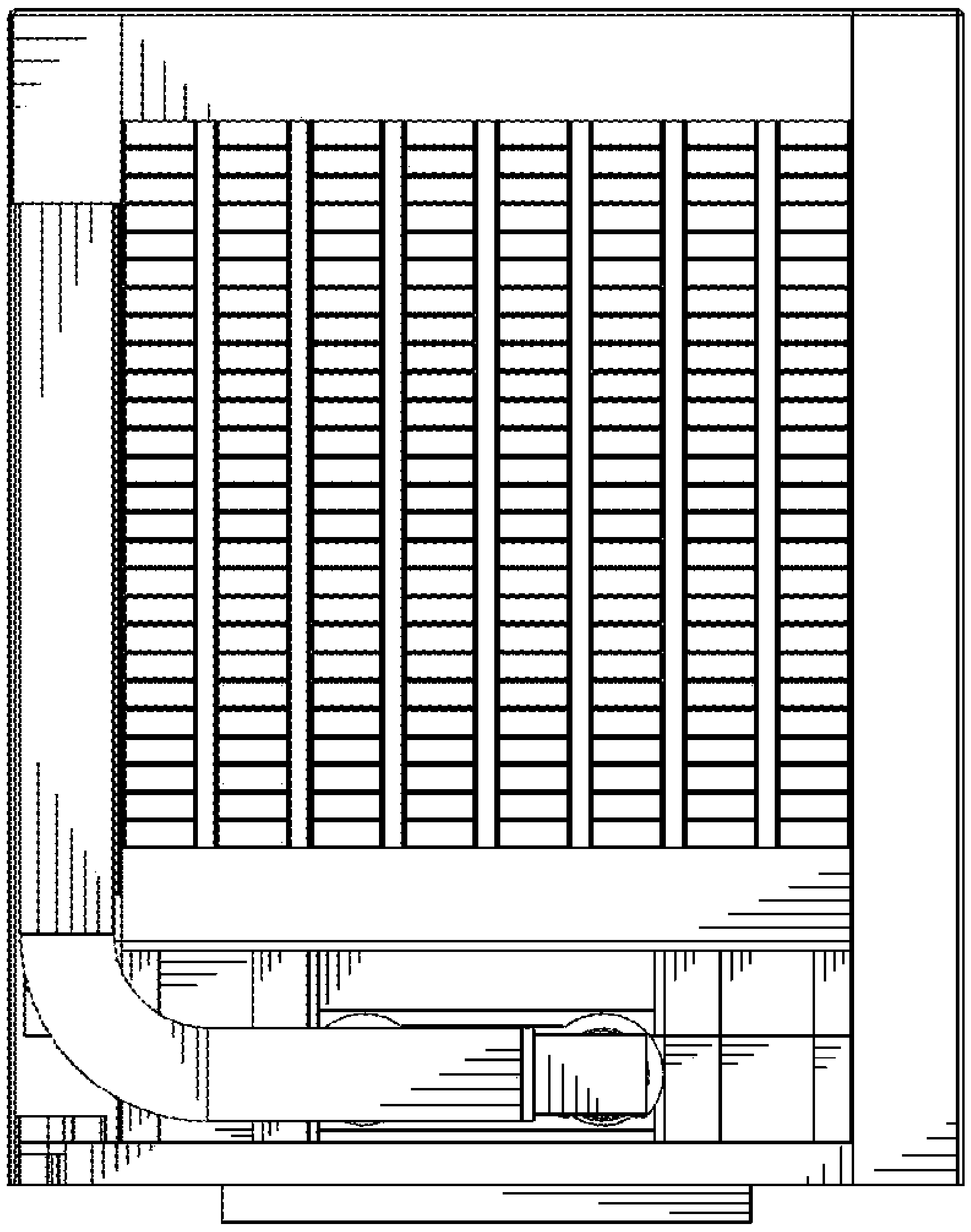


Fig. 4

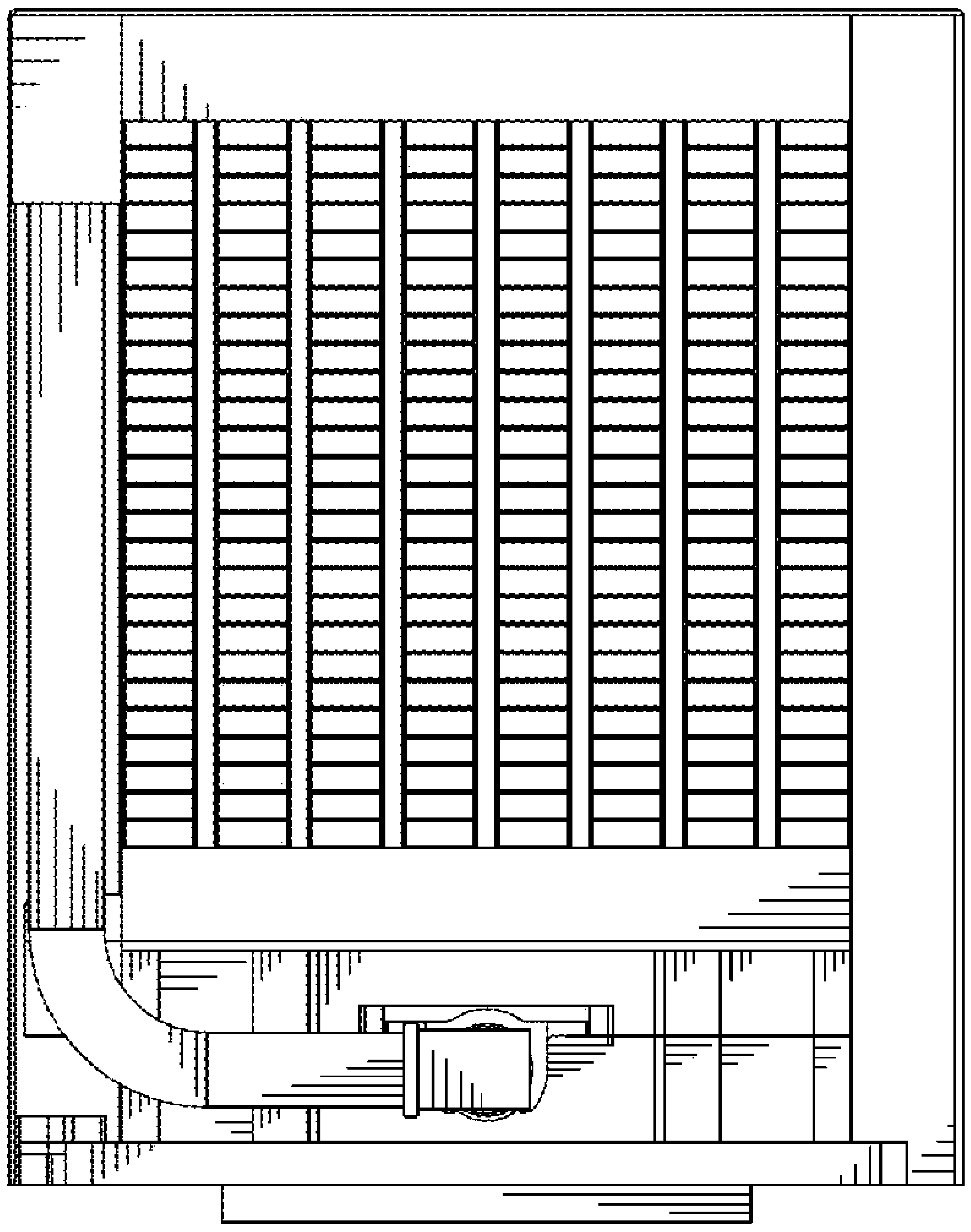


Fig. 5

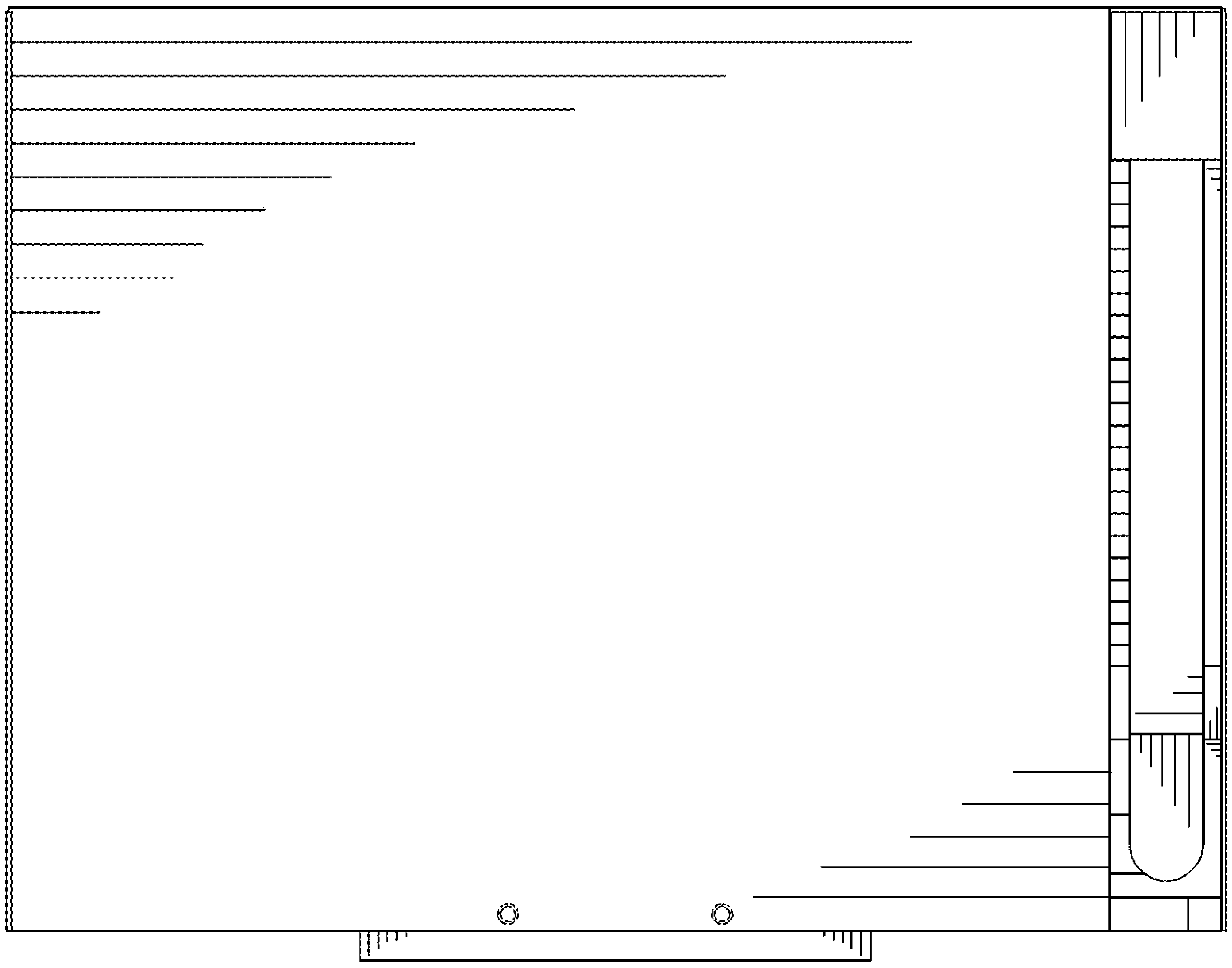
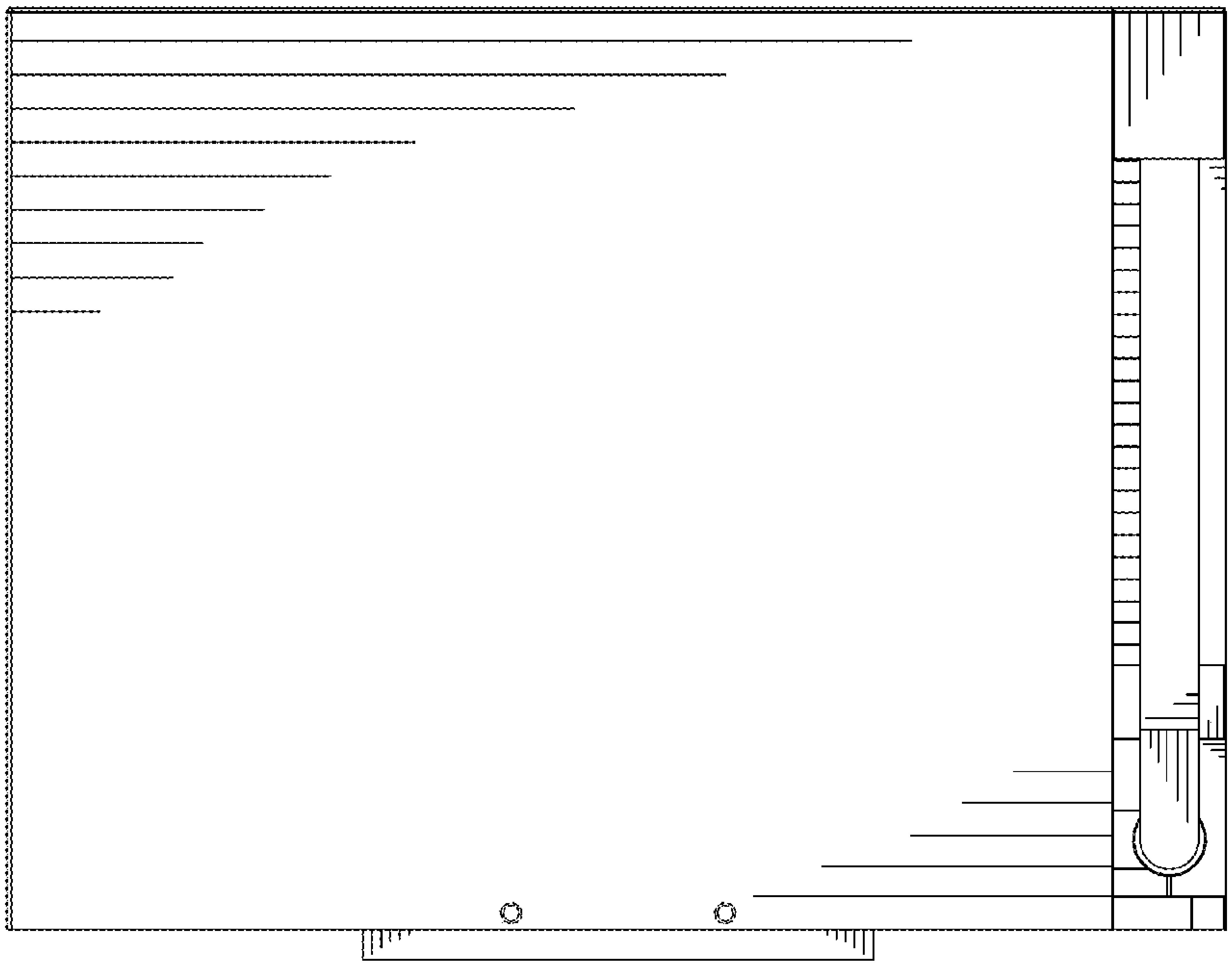


Fig. 6



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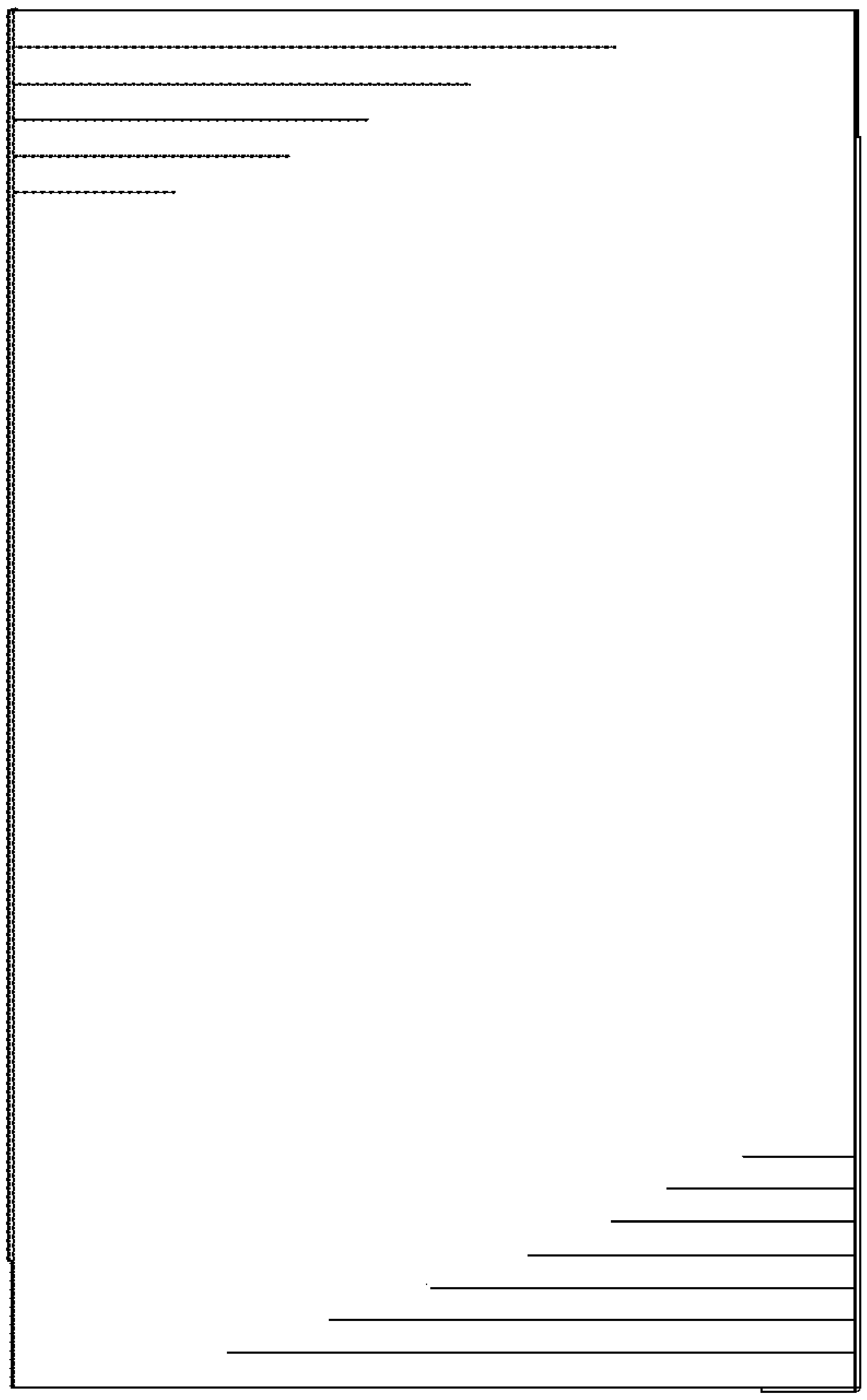

Fig. 8

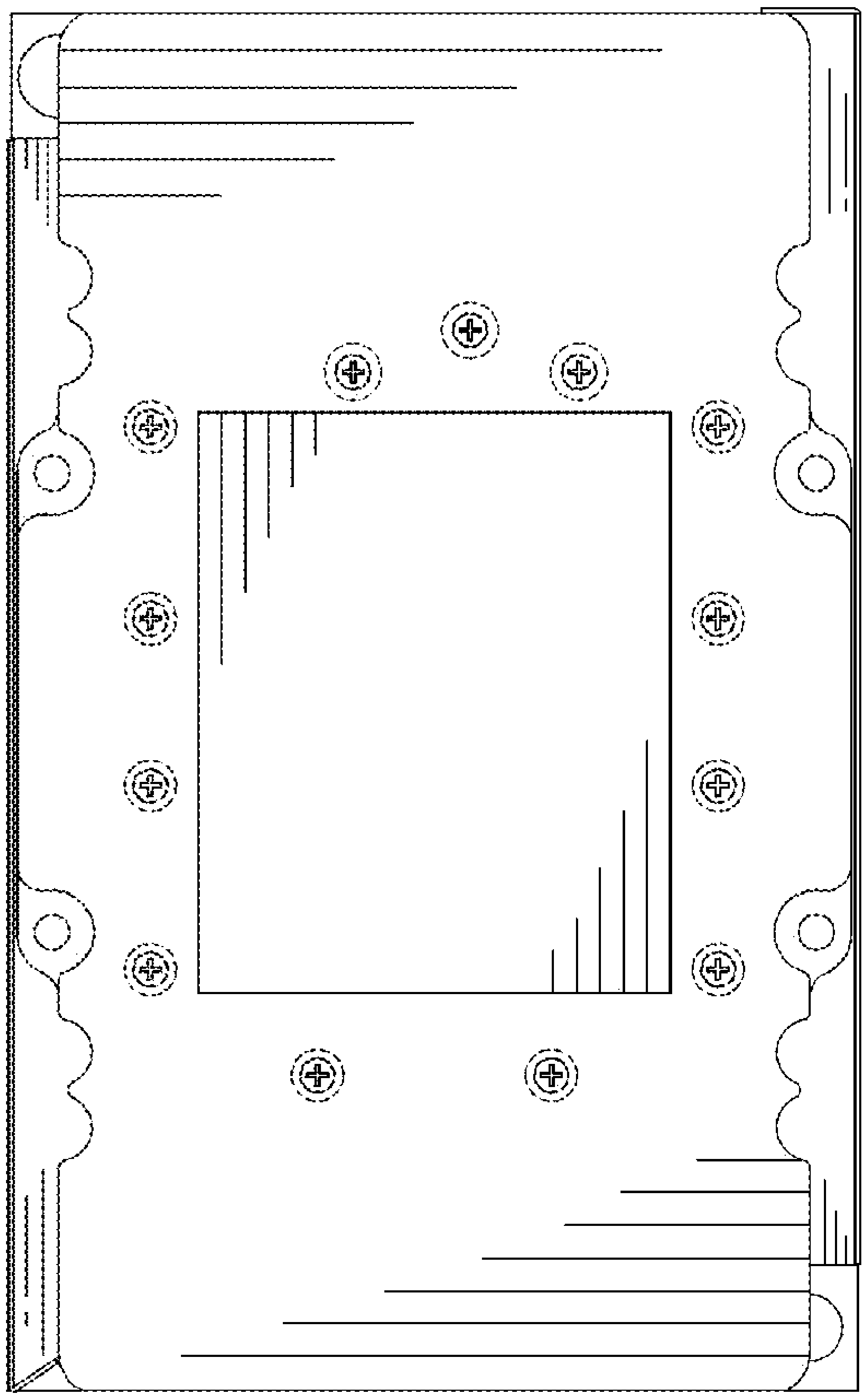

Fig. 9